

04-25-2001

Docket No.: 100/01722 (old TF-2094-01-P)



RECORDATION FORM COVER SHEET

U.S. DEPARTMENT OF COMMERCE

Patent and Trademark Office

PATENTS ONLY

101687433

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
Micromodular Data Solutions, Inc.MIZ
3.29.01

2. Name and address of receiving party(ies):

Name: Comsense Technologies, Ltd.

Address: 3 Azrieli Center

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

City: Tel Aviv

State/Prov.:

Country: Israel

ZIP: 67023

Execution Date: March 19, 2001

Additional name(s) & address(es)

☐ Yes ☒ No

4. Application number(s) or registration numbers(s):

If this document is being filed together with a new application, the execution date of the application is:

Patent Application No.

Filing date

B. Patent No.(s)

09/198,866

November 24, 1998

Additional numbers

☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: William H. Dippert, Esq.

Registration No. 26,723

Address: Cowan, Liebowitz and Latman, P.C.

1133 Avenue of the Americas

City: New York

State/Prov.: NY

Country: USA

ZIP: 10036-6799

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00

☐ Enclosed - Any excess or insufficiency should be credited or debited to deposit account☒ Authorized to be charged to deposit account

8. Deposit account number:

03-3419

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Maier FENSTER, Reg. No. 41,016

Name of Person Signing

Signature

March 22, 2001

Date

2

Total number of pages including cover sheet, attachments, and

PATENT

REEL: 011701 FRAME: 0553

100/01722 (old TF-2094-01-P)

ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, the undersigned

Micromodular Data Solutions, Inc., 1582 Norman Avenue, Santa Clara, California 95054, USA, a company incorporated under the laws of the State of California

hereby, nunc pro tunc as of the effective date of February 14, 2000, sell(s), assign(s) and transfer(s) to

Comsense Technologies, Ltd., 3 Azrieli Center, Tel-Aviv 67023, Israel, a company incorporated under the laws of the State of Israel

(hereinafter called the "Assignee"), its successors, assigns, nominees or other legal representatives, the undersigned's entire right, title and interest in and to the invention(s) titled

Reinforced Micro-Module

described and claimed in

U.S. Patent Application No. 09/198,866

filed on November 24, 1998

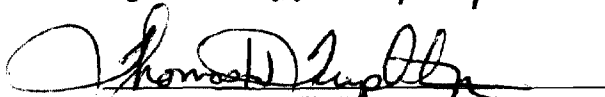
and in and to said Patent Application, and all original and reissued patents granted therefor, and any and all continuations, continuations-in-part and divisions thereof, including all extensions and reexaminations, and including the right to apply for and obtain patents in all other countries, the priority rights under International Conventions, and the Letters Patent which may be granted thereon; all rights to collect and retain all royalties and other considerations arising from said patent applications; and all rights to sue for past, present and future infringement; and the right to collect and retain all damages collected or awarded thereunder;

(I), (We) warrantee that the undersigned have (has) the full right to convey the entire interest herein assigned;

(I), (We) authorize and request the Commissioner of Patents and Trade marks, and any Official of any country whose duty it is to issue patents on applications as aforesaid, to issue said Letters Patent to said Assignee; and

(I), (We) agree to sign all lawful papers, make all rightful oaths, do all lawful acts requisite for such patent applications, and do everything possible to aid said Assignee to apply for, obtain and enforce patent protection for said invention(s).

Signed (mo/day/yr) 3/19/01 at (city) Tel Aviv, IL



Thomas H. TEMPLETON, C.E.O.
Micromodular Data Solutions, Inc.

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RECORDED: 03/29/2001

REEL: 011701 FRAME: 0554